

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	1.14	100.0	3.9
			Subtotal	1.14	100	3.9
Post-plating	Pure metal	Tin (Sn)	7440-31-5	3.5	100.0	12
			Subtotal	3.5	100	12
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	0.05
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.02	0.03	0.05
	Copper alloy	Iron (Fe)	7439-89-6	0.05	0.1	0.17
	Copper alloy	Copper (Cu)	7440-50-8	50.72	99.84	173.92
			Subtotal	50.81	100	174.19
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.61	6.0	8.96
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.05	7.0	10.45
	Filler	Silica fused	60676-86-0	37.44	86.0	128.4
	Carbon Black	Carbon black	1333-86-4	0.44	1.0	1.49
			Subtotal	43.54	100	149.3
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.09	100.0	0.3
			Subtotal	0.09	100	0.3
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.02	2.0	0.06
	Lead alloy	Silver (Ag)	7440-22-4	0.02	2.5	0.08
	Lead alloy	Lead (Pb)	7439-92-1	0.89	95.5	3.06
			Subtotal	0.93	100	3.2
			Total	100.01	100	342.89

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